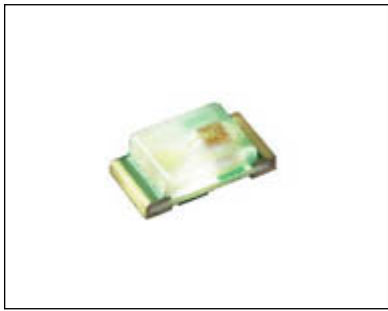




Pb-free
HEAT



1112C Series

Single Color High Brightness Type

Features

Package	1608 (h=0.5mm) Type, Milky White resin
Product features	• Outer Dimension 1.6 x 0.8 x 0.4mm (L x W x H) • Temperature range Storage Temperature : -40℃~100℃ Operating Temperature : -40℃~85℃ • Lead-free soldering compatible • RoHS compliant
Dominant wavelength	Yellow : 590nm(FY) Orange : 605nm(FA) Red : 626nm(FR)
Half Intensity Angle	FY : $\theta_x = 132 \text{ deg.}, \theta_y = 149 \text{ deg.}$ FA,FR : $\theta_x = 130 \text{ deg.}, \theta_y = 150 \text{ deg.}$
Die materials	AlGaInP
Rank grouping parameter	Sorted by luminous intensity and wavelength per rank taping
Assembly method	Auto pick & place machine (Auto Mounter)
Soldering methods	Reflow soldering and manual soldering
Taping and reel	4,000pcs per reel in a 8mm width tape. (Standard) Reel diameter: $\phi 180\text{mm}$
ESD	More than 2kV(HBM)

Recommended Applications

Cellular Phone, Electric Household Appliances, Other General Applications



1112C Series

Single Color High Brightness Type

Color and Luminous Intensity

(Ta=25°C)

Part No.	Material	Emitted Color	Lens Color	Dominant Wavelength λ_d (nm)		Luminous Intensity I_v (mcd)		
				TYP.	I_F	MIN.	TYP.	I_F
FY1112C	AlGaInP	Yellow	Milky White	590	20	25	50	20
FA1112C	AlGaInP	Orange		605	20	25	50	20
FR1112C	AlGaInP	Red		626	20	25	45	20

Absolute Maximum Ratings

(Ta=25°C)

Item	Symbol	Absolute Maximum Ratings			Unit
		FY	FA	FR	
Power Dissipation	P_d	81	81	81	mW
Forward Current	I_F	30	30	30	mA
Pulse Forward Current ※1	I_{FRM}	100	100	100	mA
Derating (Ta=25°C or higher)	ΔI_F	0.43	0.43	0.43	mA/°C
	ΔI_{FRM}	1	1	1	mA/°C
Reverse Voltage	V_R	5	5	5	V
Operating Temperature	T_{opr}	-40~+85			°C
Storage Temperature	T_{stg}	-40~+100			°C

※1 I_{FRM} Measurement condition : $t_w \leq 1\text{ms.}$, Duty $\leq 1/10$

Electro-Optical Characteristics

(Ta=25°C)

Item		Symbol	Characteristics				Unit
	Conditions			FY	FA	FR	
Forward Voltage	I _F =20mA	V _F	TYP.	1.9	1.9	1.9	V
			MAX.	2.4	2.4	2.4	
Reverse Current	V _R =5V	I _R	MAX.	100	100	100	μ A
Peak Wavelength	I _F =20mA	λ _p	TYP.	592	609	635	nm
Dominant Wavelength	I _F =20mA	λ _d	TYP.	590	605	626	nm
Spectral Line Half Width	I _F =20mA	Δ λ	TYP.	15	15	15	nm
Half Intensity Angle	I _F =20mA	2 θ 1/2	TYP.	132(θ x)	130(θ x)	130(θ x)	deg.
				149(θ y)	150(θ y)	150(θ y)	

Luminous Intensity Rank

(Ta=25°C)

Rank	I _V (mcd)					
	FY		FA		FR	
	I _F =20mA		I _F =20mA		I _F =20mA	
	MIN.	MAX.	MIN.	MAX.	MIN.	MAX.
A	25	50	25	50	25	50
B	35	70	35	70	35	70
C	50	100	50	100	50	100
D	70	140	70	140	70	140
E	100	200	100	200	100	200
F	140	-	140	-	140	-

※ Please contact our sales staff concerning rank designation.

Color Tone Groups (λd)

(Ta=25°C)

Rank	Dominant Wavelength λd (nm)			
	FY		FA	
	$I_F=20mA$		$I_F=20mA$	
	MIN.	MAX.	MIN.	MAX.
A	581.5	585.0	596.1	600.9
B	584.0	587.5	599.1	603.9
C	586.5	590.0	602.1	606.9
D	589.0	592.5	605.1	609.9
E	591.5	595.0	608.1	612.9
F	594.0	597.5		

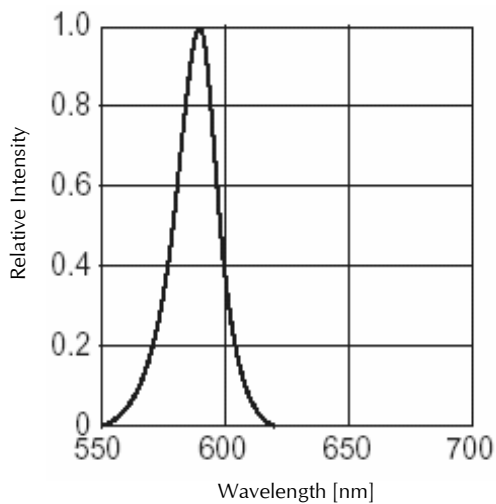
※ Please contact our sales staff concerning rank designation.

Technical Data(FY)

Spectral Distribution

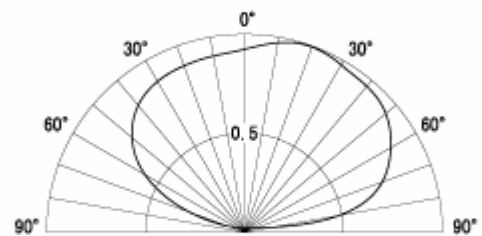
Relative Intensity vs. Wavelength

Condition : $T_a = 25^\circ\text{C}$, $I_F = 20\text{mA}$



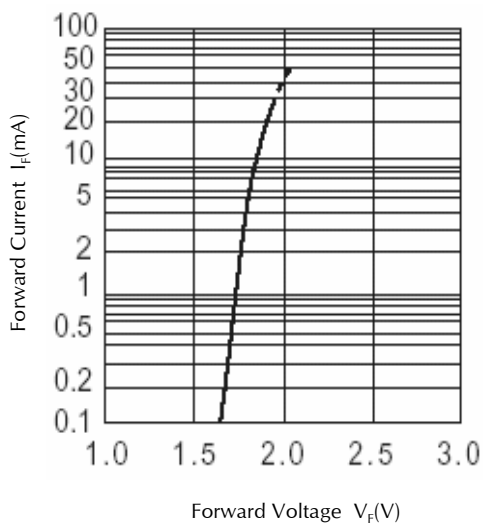
Spatial Distribution Example

Condition : $T_a = 25^\circ\text{C}$



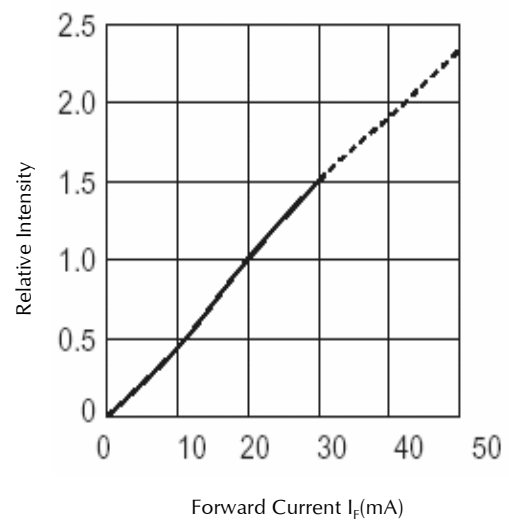
Forward Voltage vs. Forward Current

Condition : $T_a = 25^\circ\text{C}$



Forward Current vs. Relative Intensity

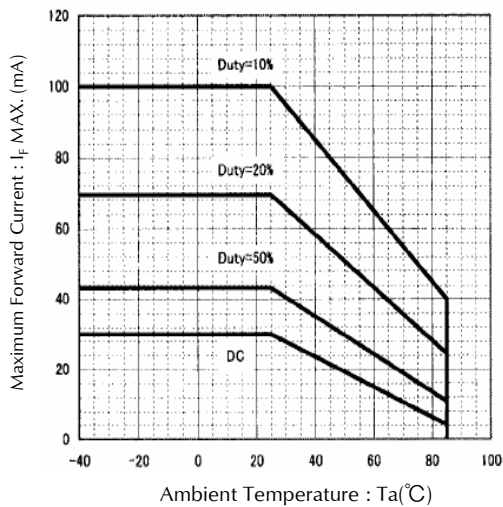
Condition : $T_a = 25^\circ\text{C}$



Technical Data(FY)

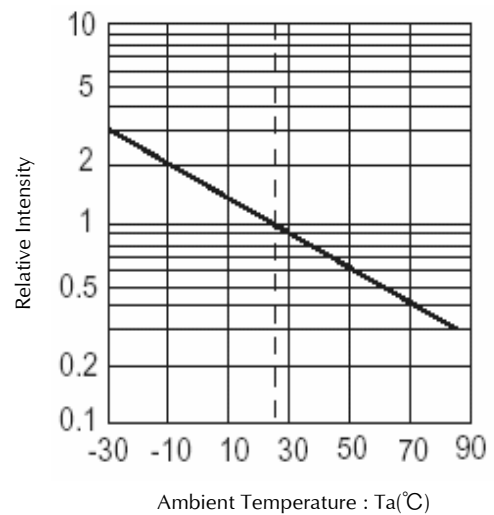
Derating

Ambient Temperature vs. Maximum Forward Current
Repetition Frequency : $f \geq 50\text{Hz}$

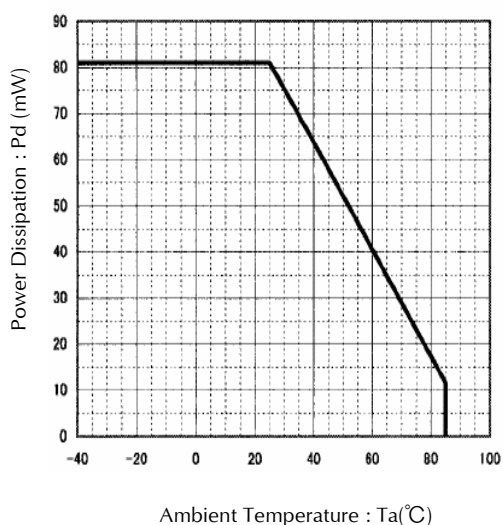


Ambient Temperature vs. Relative Intensity

Condition : $I_F=20\text{mA}$

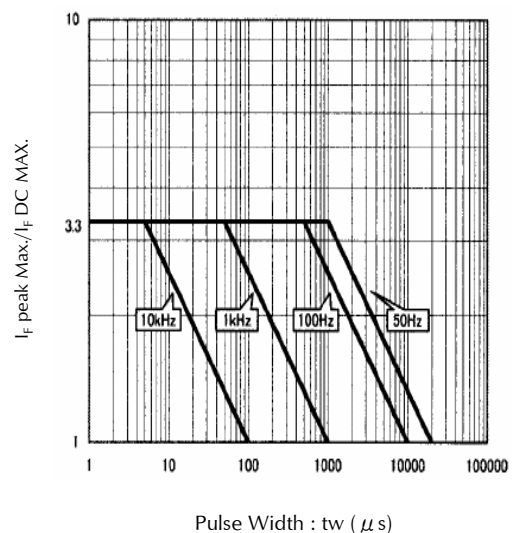


Power Dissipation vs. Ambient Temperature



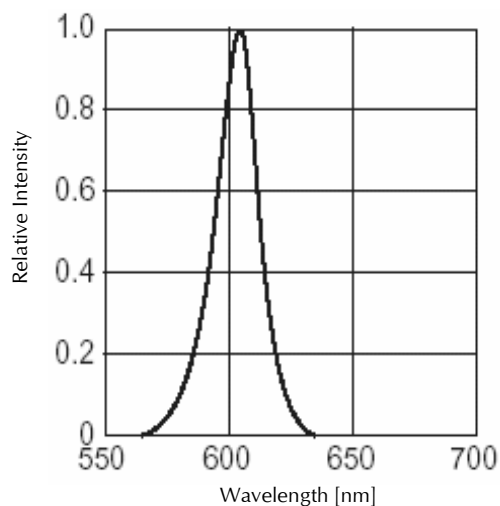
Pulse Width vs. Maximum Tolerable Peak Current

Condition : $T_a = 25^{\circ}\text{C}$



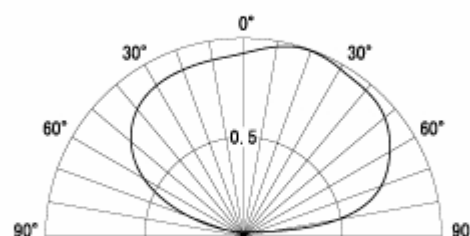
Technical Data(FA)

Spectral Distribution
Relative Intensity vs. Wavelength
Condition : $T_a = 25^\circ\text{C}$, $I_F = 20\text{mA}$

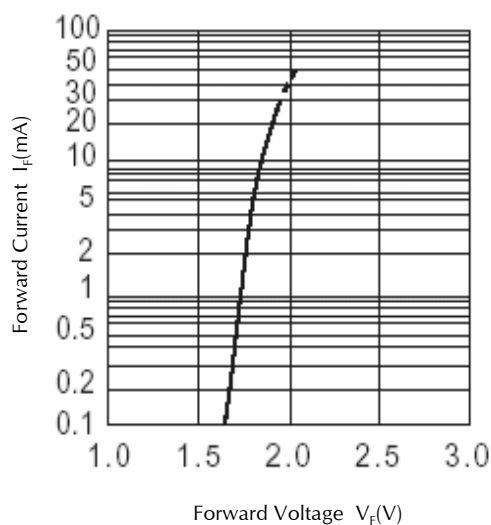


Spatial Distribution Example

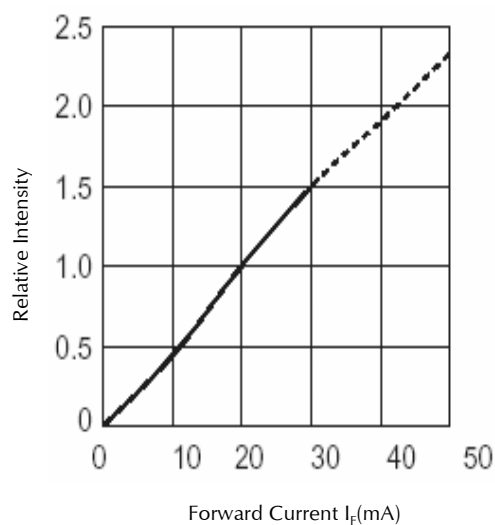
Condition : $T_a = 25^\circ\text{C}$



Forward Voltage vs. Forward Current
Condition : $T_a = 25^\circ\text{C}$



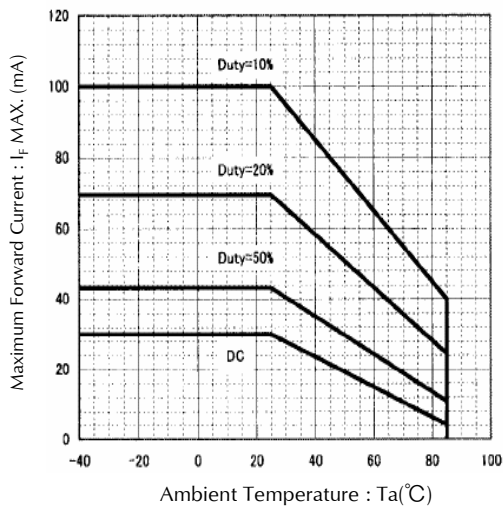
Forward Current vs. Relative Intensity
Condition : $T_a = 25^\circ\text{C}$



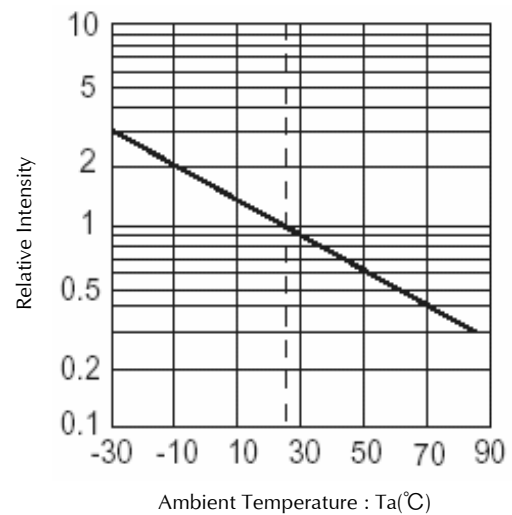
Technical Data(FA)

Derating

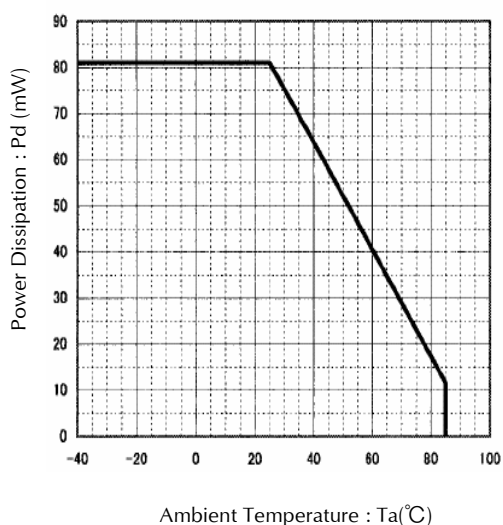
Ambient Temperature vs. Maximum Forward Current
Repetition Frequency : $f \geq 50\text{Hz}$



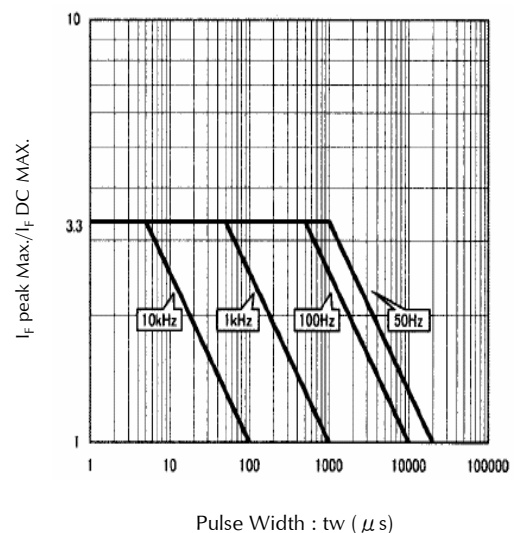
Ambient Temperature vs. Relative Intensity
Condition : $I_F=20\text{mA}$



Power Dissipation vs. Ambient Temperature



Pulse Width vs. Maximum Tolerable Peak Current
Condition : $T_a = 25^{\circ}\text{C}$

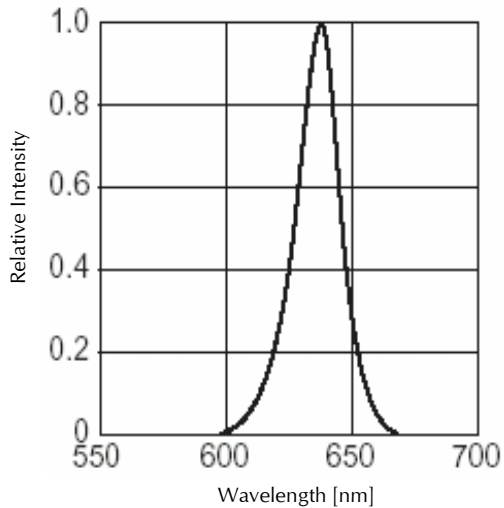


Technical Data(FR)

Spectral Distribution

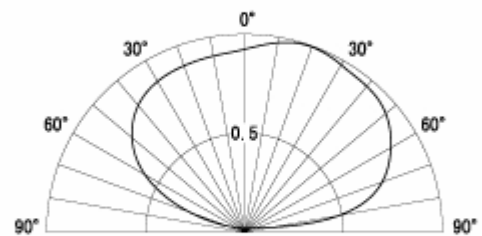
Relative Intensity vs. Wavelength

Condition : $T_a = 25^\circ\text{C}$, $I_F = 20\text{mA}$



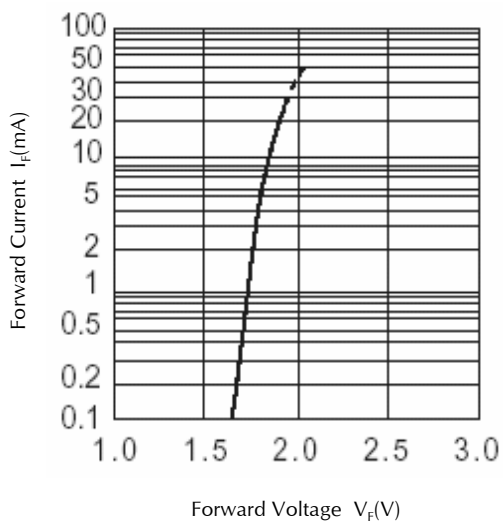
Spatial Distribution Example

Condition : $T_a = 25^\circ\text{C}$



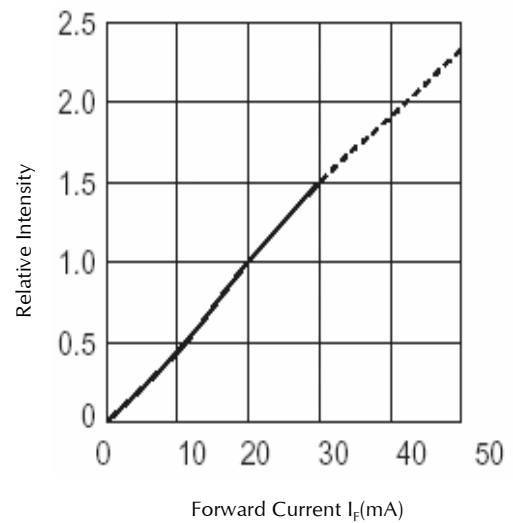
Forward Voltage vs. Forward Current

Condition : $T_a = 25^\circ\text{C}$



Forward Current vs. Relative Intensity

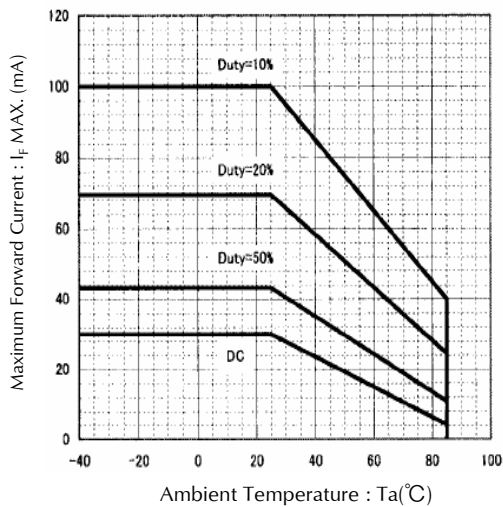
Condition : $T_a = 25^\circ\text{C}$



Technical Data(FR)

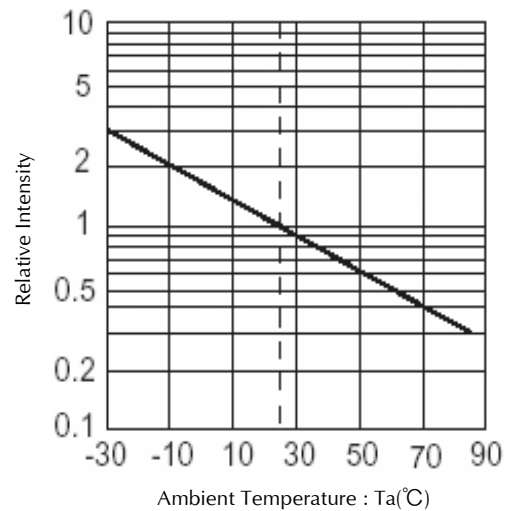
Derating

Ambient Temperature vs. Maximum Forward Current
Repetition Frequency : $f \geq 50\text{Hz}$

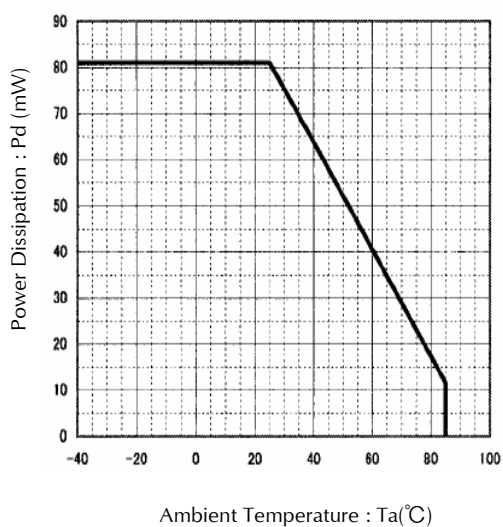


Ambient Temperature vs. Relative Intensity

Condition : $I_F=20\text{mA}$

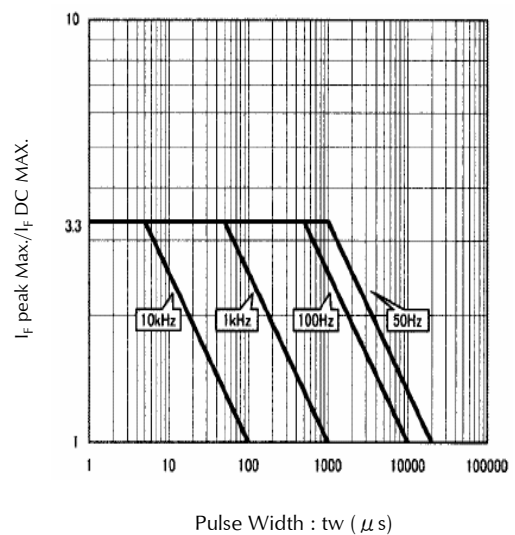


Power Dissipation vs. Ambient Temperature



Pulse Width vs. Maximum Tolerable Peak Current

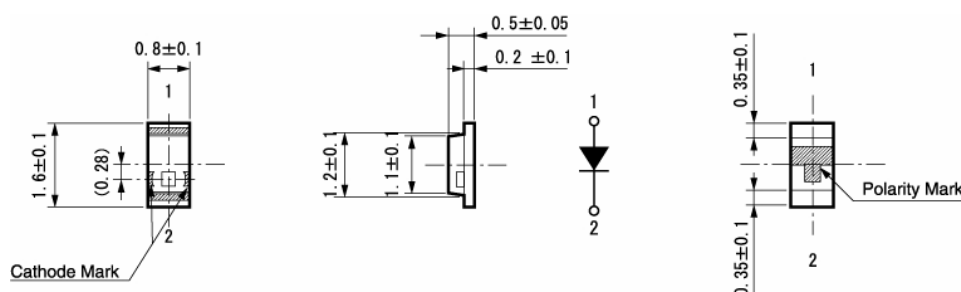
Condition : $T_a = 25^{\circ}\text{C}$



Package Dimensions

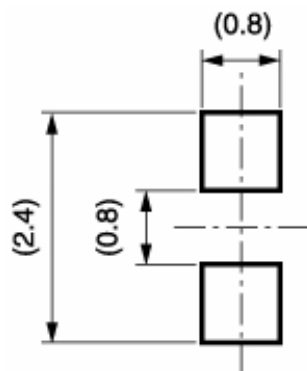
(Unit: mm)

Weight: (1.35)mg



Recommended Soldering Pattern

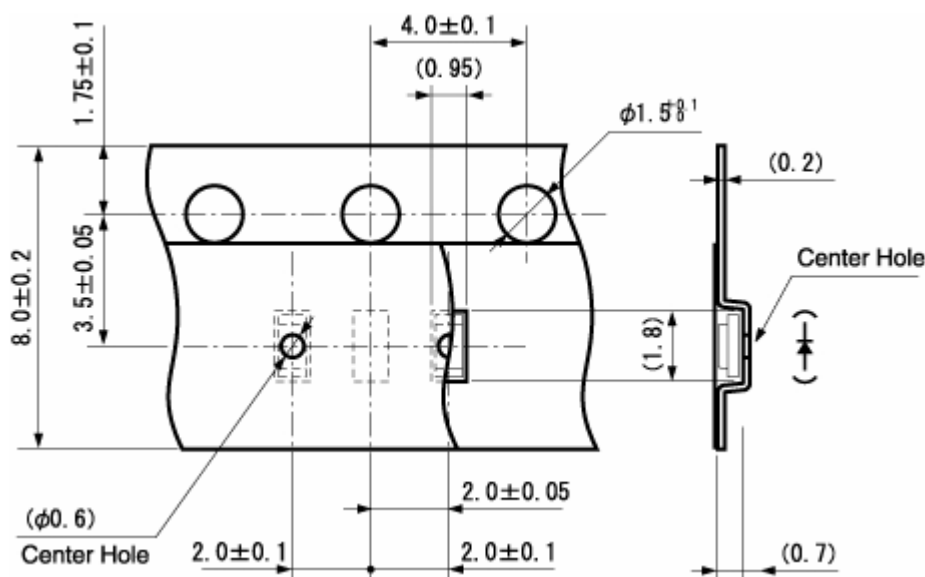
(Unit: mm)



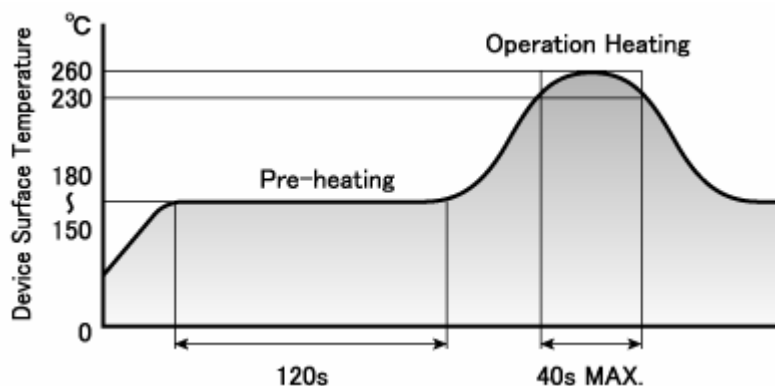
Taping Specification

(Unit: mm)

Quantity : 4,000pcs/ reel (standard)



Reflow Soldering Conditions



- 1) The above profile temperature gives the maximum temperature of the LED resin surface. Please set the temperature so as to avoid exceeding this range.
- 2) Total times of reflow soldering process shall be no more than 2 times. When the second reflow soldering process is performed, intervals between the first and second reflow should be short as possible (while allowing some time for the component to return to normal temperature after the first reflow) in order to prevent the LED from absorbing moisture.
- 3) Temperature fluctuation to the LED during the pre-heating process shall be minimized.

Manual Soldering Conditions

Iron tip temp. 350 °C (MAX.)

Soldering time and frequency 3 s (MAX.)
1 time (MAX.)

Reliability Testing Result

Reliability Testing Result	Applicable Standard	Testing Conditions	Duration	Failure
Room Temp. Operating Life	EIAJ ED-4701/100(101)	Ta = 25°C, If = Maximum Rated Current	1,000 h	0/25
Resistance to Soldering Heat	EIAJ ED-4701/300(301)	Pre-heating : 150~180°C 120s Max. Operation Heating : 230°C 40s Max. Peak Temperature : 260°C	Twice	0/25
Temperature Cycling	EIAJ ED-4701/100(105)	Minimum Rated Storage Temperature(30min) ~ Normal Temperature(15min) ~ Maximum Rated Storage Temperature(30min) ~ Normal Temperature(15min)	5 cycles	0/25
Wet High Temp. Storage Life	EIAJ ED-4701/100(103)	Ta = 60±2°C, RH = 90±5%	1,000 h	0/25
High Temp. Storage Life	EIAJ ED-4701/200(201)	Ta = Maximum Rated Storage Temperature	1,000 h	0/25
Low Temp. Storage Life	EIAJ ED-4701/200(202)	Ta = Minimum Rated Storage Temperature	1,000 h	0/25
Vibration, Variable Frequency	EIAJ ED-4701/400(403)	98.1m/s ² (10G), 100 ~ 2KHz sweep for 20min., XYZ each direction	2 h	0/10

Failure Criteria

Items	Symbols	Conditions	Failure criteria
Luminous Intensity	Iv	If Value of each product Luminous Intensity	Testing Min. Value < Spec. Min. Value x 0.5
Forward Voltage	V _F	If Value of each product Forward Voltage	Testing Max. Value ≥ Spec. Max. Value x 1.2
Reverse Current	I _R	V _R = Maximum Rated Reverse Voltage V	Testing Max. Value ≥ Spec. Max. Value x 2.5
Cosmetic Appearance	-	-	Occurrence of notable decoloration, deformation and cracking

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